

Overview

The purpose of this notification is to communicate an addition of a new supply source for Virtex®-5 FPGA flip chip BGA package core material and also announce an additional package supplier for Virtex-5 FPGA flip chip BGA package substrates.

Description

Due to the recent earthquake in Japan, there is a worldwide shortage of Bismaleimide-Triazine (BT) resin material used in the package core and build up layers of flip chip packages. To enable supply continuity Hitachi has been qualified by Xilinx as an additional source for the package core. The Hitachi core material is already in production with Virtex®-6 FPGA products. There are no changes in the form, fit or function of the package.

In addition, an additional package supplier for Virtex-5 FPGA products has been qualified. This vendor is Ibiden and is already qualified and in production with Virtex-6 FPGA product. The reason for this supplier addition is to ensure supply continuity from the Japanese earthquake. The Ibiden substrate material set also uses the Hitachi core material.

Products Affected

All Virtex-5 FPGA products are qualified to use the Hitachi core material and packages supplied by Ibiden. All product speed, package, and temperature variations of the XC commercial (C) and industrial (I) grade devices are affected. XQ, Q grade are not affected by this Product Change Notice and will not be released with the Hitachi core material or Ibiden vendor addition.

Table 1: Product Changes

Xilinx Product	Xilinx Product	Xilinx Product	Xilinx Product
XC5VLX30-FF(G)324	XC5VLX20T-FF(G)323	XC5VFX30T-FF(G)665	XCE05L11-FF(G)1153
XC5VLX30-FF(G)676	XC5VLX30T-FF(G)323	XC5VFX70T-FF(G)665	XCE05L11T-FF(G)1136
XC5VLX50-FF(G)324	XC5VLX30T-FF(G)665	XC5VFX70T-FF(G)1136	XCE05L22T-FF(G)1738
XC5VLX50-FF(G)676	XC5VLX50T-FF(G)665	XC5VFX100T-FF(G)1136	XCE05L33T-FF(G)1738
XC5VLX50-FF(G)1153	XC5VLX50T-FF(G)1136	XC5VFX100T-FF(G)1738	XC5VTX150T-FF(G)1156
XC5VLX85-FF(G)676	XC5VLX85T-FF(G)1136	XC5VFX130T-FF(G)1738	XC5VTX150T-FF(G)1759
XC5VLX85-FF(G)1153	XC5VLX110T-FF(G)1136	XC5VFX200T-FF(G)1738	XC5VTX240T-FF(G)1759
XC5VLX110-FF(G)676	XC5VLX110T-FF(G)1738	XC5VSX35T-FF(G)665	
XC5VLX110-FF(G)1153	XC5VLX155T-FF(G)1136	XC5VSX50T-FF(G)665	
XC5VLX110-FF(G)1760	XC5VLX155T-FF(G)1738	XC5VSX50T-FF(G)1136	
XC5VLX155-FF(G)1153	XC5VLX220T-FF(G)1136	XC5VSX95T-FF(G)1136	
XC5VLX155-FF(G)1760	XC5VLX220T-FF(G)1738	XC5VSX240T-FF(G)1738	
XC5VLX220-FF(G)1760	XC5VLX330T-FF(G)1738		
XC5VLX330-FF(G)1760	XC5VLX330T-FF(G)1738		
	XC5VLX330T-PF(G)1738		

Key Dates and Cross Shipping Information

Xilinx will begin to cross ship product with the additional source of substrate core material on or after April 11, 2011.

Qualification Data

Qualification data for the Hitachi core material and Ibsiden vendor addition is available.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
04/11/11	1.0	Initial release.
10/07/11	1.1	Remove “Additional Documentation” section with Qualification Report (RPT143).

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